Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	235	@ad<="20030918" and ("light emitting diode" or "LED") same encapsulat\$3 same cur\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 09:21
L3	19	@ad<="20030918" and ("light emitting diode" or "LED") same encapsulat\$3 near cur\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 09:20
L4	55	@ad<="20030918" and ("light emitting diode" or "LED") same encapsulat\$3 near3 cur\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 09:20
L7	1157	@ad<="20030918" and (438/22). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 09:40
L8	1174	@ad<="20030918" and (438/127). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 09:40
L9	223	@ad<="20030918" and (438/24). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 09:42
S1	8	(("5959316") or ("6404125") or ("5988925") or ("6066861")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 13:44
S2	160	@ad<="20030918" and 'light emitting diode' same 'coating' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 09:18
S3	10	@ad<="20030918" and 'light emitting diode' same 'cavity' with 'coated'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 14:23
S4	9	@ad<="20030918" and 'coated' with 'light emitting diode' same 'cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 14:27

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S5	7	@ad<="20030918" and 'LED' same 'mold' same 'curable'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 14:51
S6	1	"6060729".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:38
S7	1	"6001671".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:39
S8	1	"5976912".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:40
S9	1	"6001671".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:42
S10	1	"5900676".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:42
S11	1	"6001671".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:43
S12	1	"5487999".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:43
S13	1	"5474958".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:43
S14	1	"5468999".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:44
S15	1	"5436203".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:44
S16	1	"5418186".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:44
S17	1	"5851847".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:45
S18	1	"5557150".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:46
S19	1	"5557150".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:46
S20	1	"5487999".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:46
S21	1	"5474958".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:46
S22	1	"5367766".PN.	USPAT; USOCR	OR	ON	2004/11/15 14:46
S23	2	@ad<="20030918" and 'Light emitting diode' same 'mold' same 'curable'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:45
S24	10	@ad<="20030918" and 'Light emitting diode' same 'cavity' same 'curable'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 14:54

S25	43	@ad<="20030918" and 'Light emitting diode' same 'cavity' same 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:15
S26	11	@ad<="20030918" and 'Light emitting diode' same 'mold' same 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:30
S27	2069	@ad<="20030918" and (257/99-100).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:32
S28	1372	@ad<="20030918" and (257/81-82).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:33
S29	1017	@ad<="20030918" and (438/22). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 09:23
S30	198	@ad<="20030918" and (438/24). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/21 09:42
S31	295	@ad<="20030918" and (438/26). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:34
S32	163	@ad<="20030918" and (438/28). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:35
S33	191	@ad<="20030918" and (438/25). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:35
S34	208	@ad<="20030918" and (438/33). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 16:02
S35	976	@ad<="20030918" and (438/110-112).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:37

S36	1270	@ad<="20030918" and (438/125-126).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:37
S37	584	@ad<="20030918" and (313/485). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:38
S38	927	@ad<="20030918" and (313/493). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:38
S39	329	@ad<="20030918" and (313/498). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:38
S40	849	@ad<="20030918" and (313/501-503).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:38
S41	81	@ad<="20030918" and 'Light emitting diode' and 'cavity' same 'filled' same 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 15:46
S42	318	@ad<="20030918" and (438/64). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 16:02
S43	138	@ad<="20030918" and (438/68). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/15 16:02
S45	6	@ad<="20030918" and 'light emitting diode' same 'injection' adj1 'mold' same 'encapsulate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 10:07
S46	17	@ad<="20030918" and 'light emitting diode' same 'mold' same 'encapsulate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 08:55
S47	239	@ad<="20030918" and 'light emitting diode' same 'encapsulation'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 09:31

S48	12	@ad<="20030918" and 'light emitting diode' same 'encapsulation' same 'mold'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 12:03
S49	12	leung-michael.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 09:32
S50	502	leung.in. and 'chip'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 09:33
S51	11	leung.in. and 'chip fabrication'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 09:34
S52	35	ibbetson.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 09:34
S53	0	@ad<="20030918" and 'light emitting device' same 'mold' same 'encapsulate' same 'coating'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 10:08
S54	7	@ad<="20030918" and 'light emitting device' and 'mold' and 'coating' with 'curable'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 10:14
S55	32	@ad<="20030918" and 'light emitting device' and 'mold' with 'coating'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 10:18
S56	41	@ad<="20030918" and 'light emitting device' and 'mold' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 11:09
S57	22	@ad<="20030918" and 'light emitting device' and 'mold' with 'encapsulation'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 10:18
S58	39	@ad<="20030918" and 'light emitting device' and 'injection molding' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 11:15

S61	24	@ad<="20030918" and 'LED' same 'injection molding' with 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 11:21
S62	2	("4890383").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 11:21
S63	0	@ad<="20030918" and 'light emitting diode' same 'encapsulation' with 'light conversion particles'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 12:03
S64	5	@ad<="20030918" and 'light emitting device' same 'light conversion' with 'material'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/16 12:04
S66	477	@ad<="20030918" and 'light emitting diodes' and 'encapsulation' and 'cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 11:39
S68	173	@ad<="20030918" and 'LEDS' and 'encapsulation' and 'mold' with 'cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 14:15
S69	1	"20030160256".PN.	US-PGPUB	OR	ON	2005/05/03 10:44
S70	1	"20010030866".PN.	US-PGPUB	OR	ON	2005/05/03 10:45
S71	1	"6331063".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:45
S72	1	"6132072".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:47
S73	1	"6069440".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:49
S74	1	"6066861".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:49
S75	1	"5998925".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:49
S76	1	"5966393".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:49
S77	1	"5931577".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:50
S78	1	"5925897".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:51
S79	1	"5898185".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:52

S80	1	"5895932".PN.	USPAT; USOCR	OR	ON	2005/05/03 10:52
S81	11	@ad<="20030918" and 'light emitting diodes' and 'cure' same 'polymer' and 'mold cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/03 11:40
S83	176	@ad<="20030918" and 'LED' and 'encapsulation' and 'mold' with 'cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 14:17
S84	84	@ad<="20030918" and 'light emitting diode' and 'encapsulation' and 'mold' with 'cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 14:51
S85	1	"5895967".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:23
S86	1	"5719440".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:23
S87	1	"5608262".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:23
S88	1	"5598096".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:23
S89	1	"5420460".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:24
S90	1	"5910687".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:25
S91	1	"5900676".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:25
S92	1	"5886398".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:26
S93	1	"5719440".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:26
S94	1	"5391346".PN.	USPAT; USOCR	OR	ON	2005/09/23 14:28
S95	14	@ad<="20030918" and 'encapsulation' with 'light emitting diode' and 'mold' with 'cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 15:10
S96	16	@ad<="20030918" and 'encapsulated' with 'light emitting diode' and 'mold' with 'cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 15:10
S97	5	@ad<="20030918" and 'seal' with 'light emitting diode' and 'mold' with 'cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 15:14

S98	33	@ad<="20030918" and 'seal' with 'light emitting diode' and 'cavity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 15:18
S99	652	@ad<="20030918" and 'molded' with 'light emitting diode'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 15:43

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